

Specifications for the 6 Layer PCB fabrication:

1. THE ORDER SHOULD NOT BE PREFERABLY SPLIT. THE COMPREHENSIVE QUOTE CONSIDERING FABRICATION/FITMENT OF ALL COMPONENTS, FOR AT CSIO WILL BE CONSIDERED.
2. THE REQUIRED QUANTITY IS MENTIONED AGAINST EACH COMPONENT IN ANNEXURE 1. THE COMPONENTS SHOULD BE SEALED /PACKED AS PER THE ORIGINAL FACTORY PACKING. IF FOUND DAMAGED, WILL BE RETURNED.
3. THE PRICE SHOULD BE INCLUDING EX-CSIO DELIVERY.
4. THE VALID COC/INSPECTION REPORT SHOULD BE SHARED WHEREVER APPLICABLE.
5. THE SUPPLIER SHOULD SHARE THE AUTHORIZATION LETTER FROM THE OEM, WHEREVER APPLICABLE
5. PAYMENT AND OTHER THINGS AS PER CSIO NORMS
6. PL MAIL AT head.pme@csio.res.in, mis@csio.res.in and hemant.ajal@csio.res.in
7. QUOTE TIME 7 DAYS FROM THE DATE OF TENDER.
8. THE DETAILS OF THE USER WILL NOT BE SHARED.
9. SUPPLIER TO SHARE THE DELIVERY TIMELINES AFTER PO AND PAYMENT TERMS. RELEASE OF PO IS PURELY THE PREROGATIVE OF CSIO.

Specifications of the 6 Layer PCB:

Dimensions: 234 X125 mm

Layers: 6

Inner Layer \geq 35 microns

Outer Layer \geq 35 micron

Minimum conductor Width: 0.3 mm

Minimum conductor Spacing: 0.21 mm

Minimum Hole Diameter: 0.5 mm

PCB Material: FR4

PCB Surface Finish: HAL Tin Lead

Silk Screen Non-Conductive White Epoxy Ink (Both Sides)

Controlled Impedance: No

Test Coupons: No

P.S.: GERBER Data will be shared along with the P.O.